



(0.40 mm) .0158"

ULTRA FINE PITCH SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?SS4

Insulator Material:

Black LCP

Contact Material:

Phosphor Bronze

Plating:

Au or Sn over

50µ" (1.27 µm) Ni

Operating Temp Range:

-55°C to +125°C

Current Rating:

1.6 A per pin

(1 pin powered per row)

RoHS Compliant:

Yes

Processing:

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

(0.10 mm) .004" max

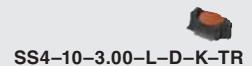
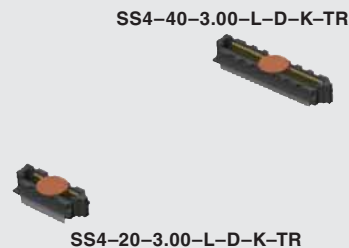
Mates with:
ST4

RECOGNITIONS

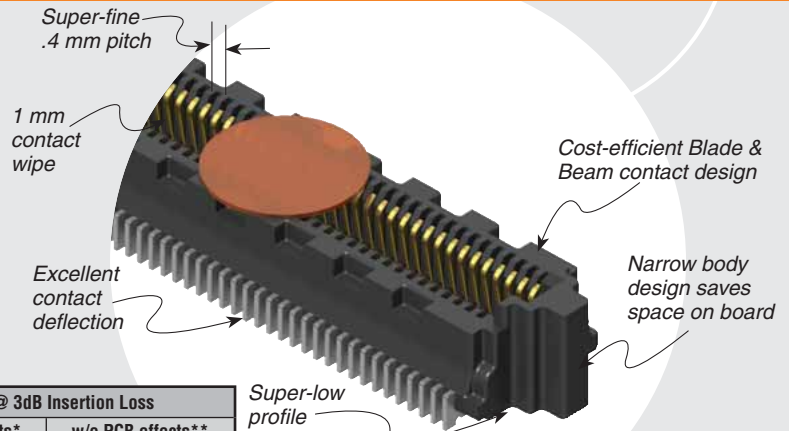
For complete scope of recognitions see www.samtec.com/quality



FILE NO. E111594



SS4 SERIES



SS4/ST4 4 mm Stack Height	Rated @ 3dB Insertion Loss	
	with PCB effects*	w/o PCB effects**
Single-Ended Signaling	7.0 GHz / 14 Gbps	13.5 GHz / 27 Gbps
Differential Pair Signaling	4.5 GHz / 9 Gbps	15.5 GHz / 31 Gbps

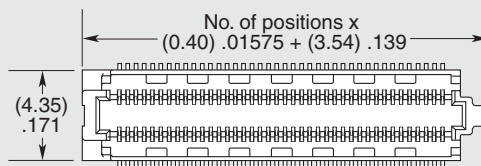
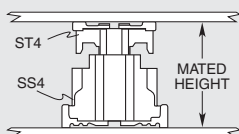
*Performance data includes effects of a non-optimized PCB.
**Test board losses de-embedded from performance data.

Performance data for other stack heights and complete test data available at www.samtec.com?SS4 or contact sig@samtec.com

Finalinch
CERTIFIED | 28+ Gbps

SS4	POSITIONS PER ROW	LEAD STYLE	PLATING OPTION	D	K	TR
	-10, -20, -30, -40, -50	-3.00 = 3.00 mm -3.50 = 3.50 mm	-L = 10µ" (0.25 µm) Gold on contact, Matte Tin on tail		(Required in callout) -K = (3.51 mm) .138" DIA Polyimide Film Pick & Place Pad	(Required in callout) -TR = Tape & Reel

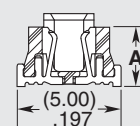
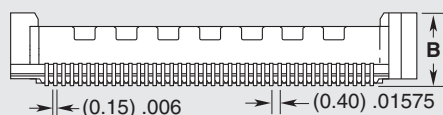
MATED HEIGHT



LEAD STYLE	A	B
-3.00	(2.85) .112	(3.50) .138
-3.50	(3.35) .132	(4.00) .157

MATED HEIGHT*			
SS4 LEAD STYLE	ST4 LEAD STYLE		
	-1.00	-1.50	-2.50
-3.00	(4.00) .157	(4.50) .177	(5.50) .217
-3.50	(4.50) .177	(5.00) .197	(6.00) .236

*Processing conditions will affect mated height.



Note: Some lengths, styles and options are non-standard, non-returnable.